

# bq27530EVM with bq27530 Battery Management Unit Impedance Track<sup>™</sup> Fuel Gauge and bq24161 2.5-A, Dual-Input, Switch-Mode Battery Charger for Single-Cell Applications

This evaluation module (EVM) is a complete evaluation system for the Battery Management Unit (BMU) chipset consisting of the bq27530-G1 fuel gauge and bq24161 battery charger. The EVM includes one bq27530 circuit, including a current sense resistor and one thermistor. In addition, the fuel gauge controls the bq24161 battery charger's settings and monitors its status via I<sup>2</sup>C communication lines. Together, the chipset provides all necessary components to monitor and predict capacity for a system-side fuel gauge solution as well as to charge the battery from either an adapter or USB input with up to 2.5-A of charge current. The circuit module connects directly across the battery pack. With the EV2300 interface board and software, the user can read the bq27530-G1 data registers, program the chipset for different pack configurations, log cycling data for further evaluation, and evaluate the overall functionality of the battery management unit solution under different charge and discharge conditions. The latest Microsoft® Windows® based PC software can be downloaded from the product folder on the Texas Instruments Web site.

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#### 1 Features

- Complete evaluation system for the Battery Management Unit chipset consisting of the bq27530-G1 Impedance Track fuel gauge and bq24161 2.5-A Dual Input Battery Charger.
- Populated circuit module for quick setup
- Personal computer (PC) software and interface board for easy evaluation
- Software that allows data logging for system analysis
- · Ability to upgrade to the latest firmware version by flash reprogramming

### 1.1 Kit Contents

2

- bq27530-G1 and bq24161 chipset circuit module (HPA763)
- NTC103AT thermistor

This EVM is used for the evaluation of the bq27530-G1 and bq24161 BMU chipset. Ensure that you visit the product Web folder at www.ti.com to download the latest firmware version, evaluation software, and documentation for the associated product to be evaluated.

#### 1.2 Ordering Information

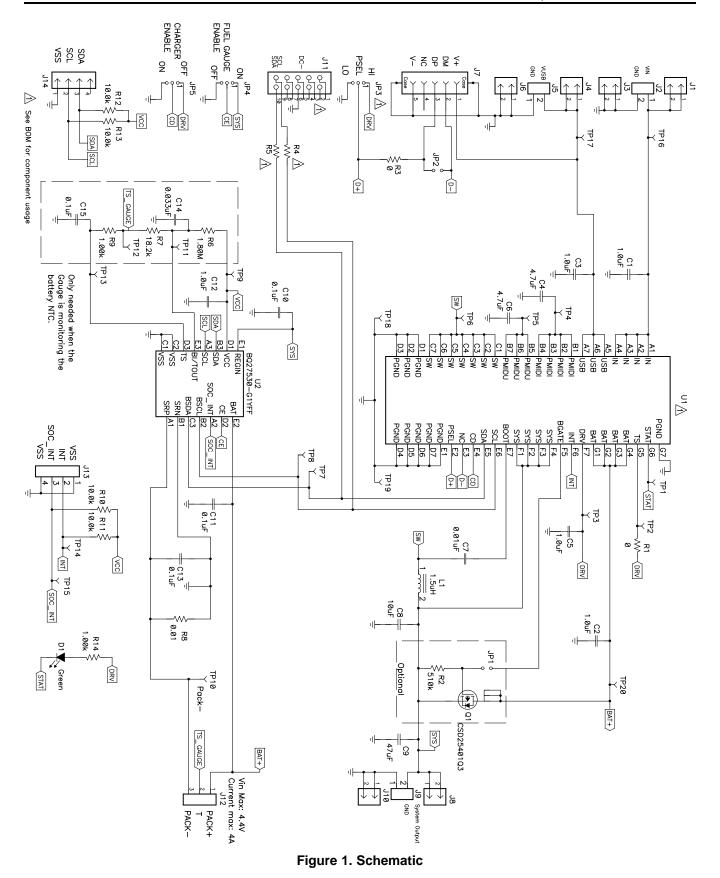
Table	1.	Ordering	Information
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EVM PART NUMBER	CHEMISTRY	CONFIGURATION	CAPACITY
bq27530EVM	Li-ion	1 cell	Any

### 2 bq27530-Based Circuit Module

The bq27530-based circuit module is a complete and compact example solution of a bq27530 circuit for battery management. The circuit module incorporates a bq27530 battery gas gauge integrated circuit (IC) and all other components necessary to accurately predict the capacity of 1-series Li-ion cell.







#### bq27530-Based Circuit Module

### 2.1 Circuit Module Connections

Contacts on the circuit module provide the following connections:

- Direct connection to the battery pack (J2 or J3): PACK+, PACK-, and TS
- To the serial communications port (J8): SDA, SCL, and VSS
- The system load and charger connect across charger and load (J6 and J7): CHARGER-/LOAD- and CHARGER+/LOAD+.
- Access to signal outputs (J5): SOC\_INT, BAT\_GD, and BAT\_LOW

# 2.2 I/O Description

Header/Terminal Block	Description		
J1–VIN	Adapter positive terminal		
J2–VIN	Adapter positive terminal		
J2–GND	Adapter negative terminal		
J3-GND	Adapter negative header		
J4-USB	USB positive header		
J5-USB	USB positive terminal		
J5-GND	USB negative terminal		
J6-GND	USB negative header		
J7	USB Miniconnector		
J8-SYS	System positive header		
J9-SYS	System positive terminal		
J9-GND	System negative terminal		
J10-GND	System ground header		
J10-SYS	System output positive header		
J11	USBTOGPIO 10-pin connector (not installed)		
J12-PACK+	Battery positive terminal		
J12-T	Pack thermistor input that leads to IC TS pin		
J12-PACK-	Battery negative terminal		
J13	I2C SDA/SCL/VSS - I2C communication header		
J14	EV2300 connector for using bq27530 software to communicate with bq27530 IC		

# 2.3 Test Points

Test Point	Description			
TP1	bq24161 STAT pin			
TP2	bq24161 TS pin			
TP3	bq24161 DRV pin			
TP4	bq24161 PMIDI pin			
TP5	bq24161 PMIDU pin			
TP6	bq24161 SW pin			
TP7	bq24161 SDA = bq27530 BSDA - I2C communication data line			
TP8	bq24161 SCL = bq27530 BSCL - I2C communication clock line			
TP9	bq27530 VCC			
TP10	bq27530 PACK-			
TP11	bq27530 BI/TOUT			
TP12	Battery pack NTC positive side			
TP13	bq27530 TS pin			
TP14	bq24161 INT pin			

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Test Point	Description
TP15	bq27530 SOC_INT pin - Access to open-drain output that signals interrupt for changes in SOC.
TP16	bq24161 IN voltage
TP17	bq24161 USB voltage

# 2.4 Control and Key Parameters Setting

Jumper	Description	Default Factory Setting
JP1 BGATE	When installed, connects the bq24161's BGATE output to the gate of Q1, thereby enabling the external battery FET.	INSTALLED
JP2 USB D+/D-	Shorting jumper for USB data lines DM (D-) and DP (D+). When shorted, USB input current limit defaults to 1.5 A. Otherwise, USB100 mode is selected.	NOT INSTALLED
JP3 PSEL		
JP4 CHARGE ENABLE	2-3 ON: Charge disable (CD) pin low for normal operation 1-2 OFF: Charge disable (CD) pin high to disable charge and enter Hi-Z mode	1-2 OFF
JP5 FUEL GAUGE ENABLE	1-2 ON: Charge enable (CE) pin high for normal operation 2-3 OFF: Charge enable (CE) pin low to disable charge and gauging	2-3 OFF



#### 3 **Circuit Module Physical Layouts, Bill of Materials, and Schematic**

This section contains the board layout, bill of materials, assembly drawings, and schematic for the bq27530 circuit module.

#### 3.1 **Board Layout**

This section shows the printed-circuit board (PCB) layers (Figure 2 through Figure 5), assembly drawing, and schematic for the bg27530 module.

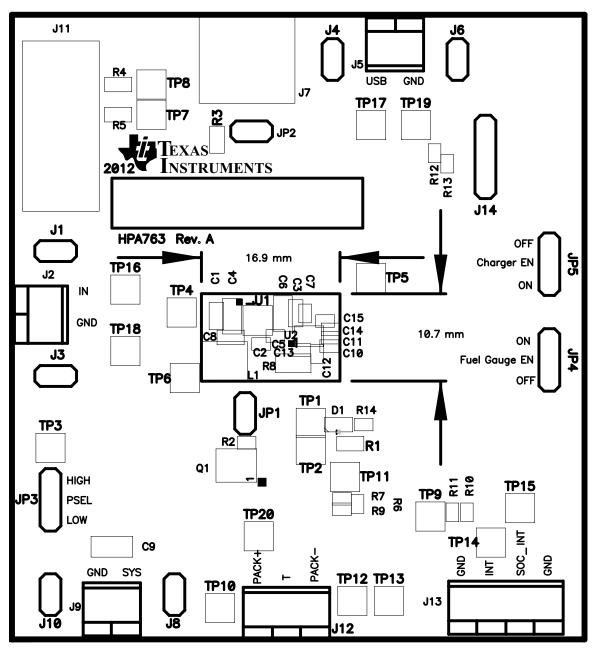


Figure 2. bq27530EVM-001 Layout – Layer 1 Silk Screen

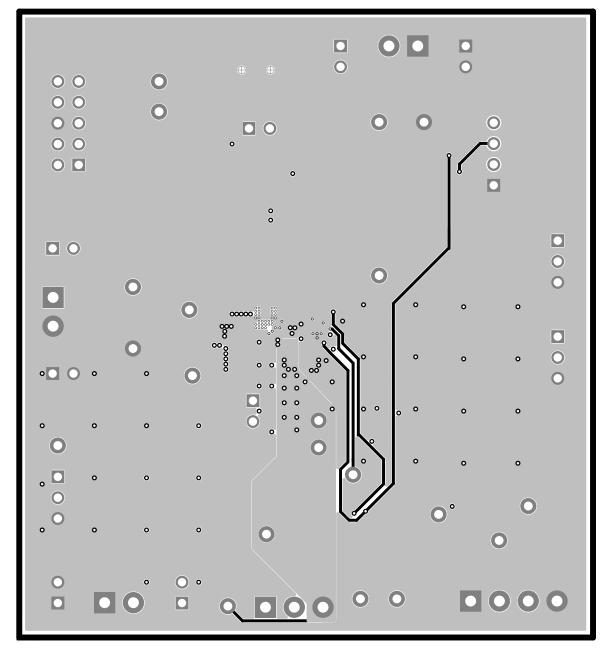


Figure 3. Layer 2



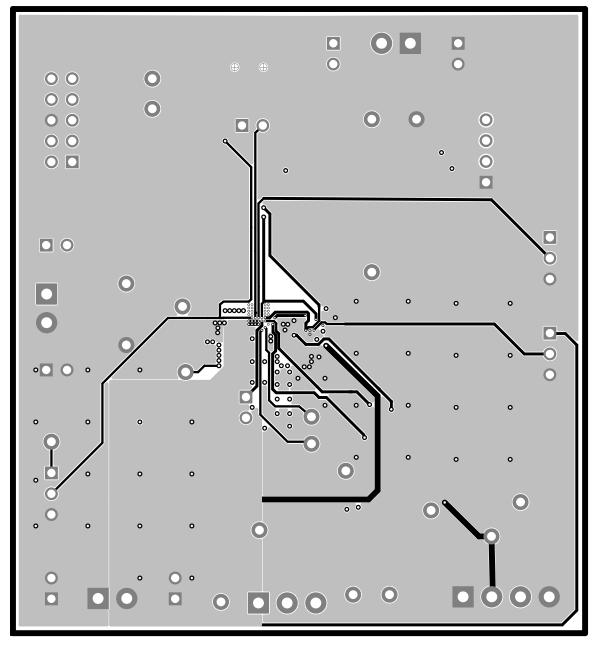


Figure 4. Layer 3

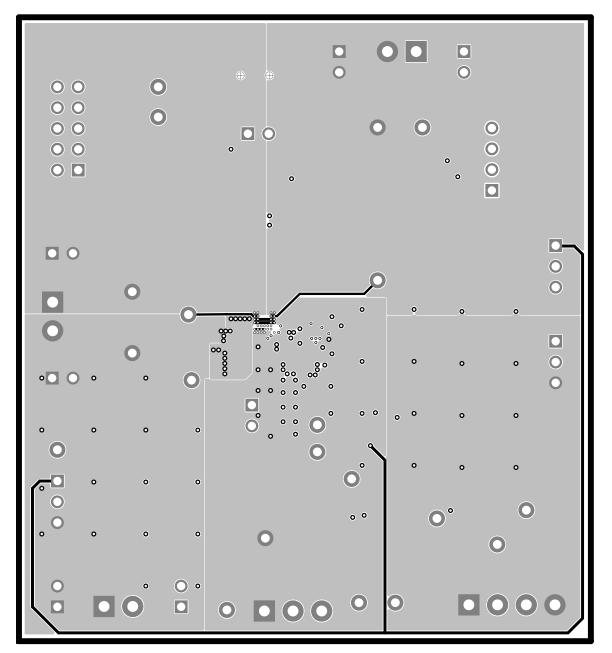


Figure 5. Layer 4



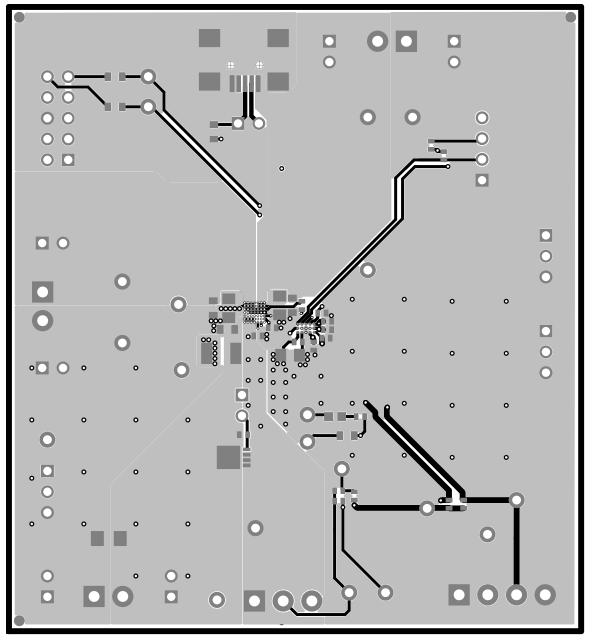


Figure 6. Layer 5



# 3.2 Bill of Materials and Schematic

Count	Reference Designator	Value	Description	Size	Part Number	MFR
2	C1, C3	1.0uF	Capacitor, Ceramic, 25V, X5R, 10%	0603	Std	Std
3	C2, C5, C12	1.0uF	Capacitor, Ceramic, 6.3V, X5R, 10%	0402	Std	Std
2	C4, C6	4.7uF	Capacitor, Ceramic, 25V, X5R, 10%	0805	Std	Std
1	C7	0.01uF	Capacitor, Ceramic, 16V, X7R, 10%	0402	Std	Std
1	C8	10uF	Capacitor, Ceramic, 10V, X5R, 10%	0603	Std	Std
1	C9	47uF	Capacitor, Ceramic, 10V, X5R, 20%	1206	Std	Std
4	C10, C11, C13, C15	0.1uF	Capacitor, Ceramic, 6.3V, X5R, 10%	0402	Std	Std
1	C14	0.033uF	Capacitor, Ceramic, 16V, X7R, 10%	0402	Std	Std
1	D1	Green	Diode, LED, Green, 2.1-V, 20-mA, 6-mcd	0603	LTST-C190GKT	Liteon
6	J1, J3, J4, J6, J8, J10	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
0	J11	Open	Connector, Male Straight 2x5 pin, 100mil spacing, 4 Wall	0.338 x 0.788 inch	N2510-6002-RB	3М
1	J12	ED555/3DS	Terminal Block, 3-pin, 6-A, 3.5mm	0.41 x 0.25 inch	ED555/3DS	OST
1	J13	ED555/4DS	Terminal Block, 4-pin, 6-A, 3.5mm	0.55 x 0.25 inch	ED555/4DS	OST
1	J14	22-05-3041	Header, Friction Lock Ass'y, 4-pin Right Angle	0.400 x 0.500	22-05-3041	Molex
3	J2, J5, J9	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED555/2DS	OST
1	J7	UX60-MB-5ST	Connector, Recpt, USB-B, Mini, 5-pins, SMT	0.354 X 0.303 Inches	UX60-MB-5ST	Hiroise
2	JP1, JP2	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
2	JP4, JP5	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
1	JP3	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
1	L1	1.5uH	Inductor, SMT, 3.5A, 70 milliohm	4.1x4.4 mm	SPM4012T-1R5M Alternate: FDSD0415-H- 1R5M	TDK Alternate: Toko
1	Q1	CSD25401Q3	MOSFET, PChan, -20V, 60A, 8.7 milliOhm	QFN3.3X3.3mm	CSD25401Q3	ТІ
1	R1	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	R3	0	Resistor, Chip, 1/16W, 1% 0603 Std		Std	
4	R10, R11, R12, R13	10.0k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R2	510k	Resistor, Chip, 1/16W, 1% 0402 Std		Std	Std
0	R4, R5	Open	Resistor, Chip, 1/16W, 1% 0603 Std		Std	Std
1	R6	1.80M	Resistor, Chip, 1/16W, 1%	0402	Std	Std

#### Table 2. Bill of Materials



Table 2	. Bill of	Materials	(continued)
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Count	Reference Designator	Value	Description	Size	Part Number	MFR
1	R7	18.2k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R8	0.01	Resistor, Chip, 1/4W, 1%	0805	WSL0805R0100FEA18	Vishay
2	R9, R14	1.00k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
20	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13, TP14, TP15, TP16, TP17, TP18, TP19, TP20	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
1	U1	BQ24161YFF	IC, 2.5A, Dual-Input, Single Cell SwitchmodeLi-Ion BATTERY CHARGER with Power Path Management	BGA	BQ24161YFF	TI
1	U2	BQ27530- G1YZF	IC, Battery Monitor and Data Logger	DSBGA	BQ27530-G1YZF	TI
4			Shunt, 100-mil, Black	0.100	929950-00	3M
1			PCB		HPA763	Any
1			Label (See note 5)	1.25 x 0.25 inch	THT-13-457-10	Brady
2	J5 mate		Connector, Female, 0.100 Centers		22-01-3047	Molex
8	N/A		Terminals, Crimp, Tin		08-50-0114	Molex
	N/A		Wire, Insulated 24 Awg, Red, 18 Inches (+/- 3 inches)(USB_5V)		1854-3	Alpha
	N/A		Wire, Insulated 24 Awg, White, 18 Inches (+/- 3 inches)(SCL)		1854-1	Alpha
	N/A		Wire, Insulated 24 Awg, Black, 18 Inches (+/- 3 inches)(GND)		1854-2	Alpha
	N/A		Wire, Insulated 24 Awg, Brown, 18 Inches (+/- 3 inches) (SDA)		1854-7	Alpha
1	N/A		Heatshrink 1" placed at middle of wire set		Any	Any

# 3.3 bq27530 Circuit Module Performance Specification Summary

This section summarizes the performance specifications of the bq circuit module.

# 3.4 Recommended Operating Conditions

		Min	Тур	Max	Unit
Supply voltage, V <sub>IN</sub>	Input voltage from ac adapter	4.2		10	V
USB voltage, V <sub>USB</sub>	Input voltage from USB or equivalent supply	4.2		6	V
System voltage, V <sub>SYS</sub>	Voltage output at SYS terminal (depends on VBAT voltage and status of $V_{\rm INDPM}$ and input current limit circuits)	3.3		VBATR EG+4.17 %	V
Battery voltage, $V_{BAT}$	Voltage output at VBAT terminal (registers set via bq27530 software)	3	4.2	4.44	V
Supply current, $I_{IN(MAX)}$	Maximum input current from ac adapter input (registers set via bq27530 software)	1.5		2.5	A
Supply current, $I_{USB(MAX)}$	Maximum input current from USB input (registers set via bq27530 software)	0.1	0.5	1.5	А
Fast charge current, I <sub>CHRG(MAX)</sub>	Battery charge current (registers set via bq27530 software)	0.550		2.5	A
Operating junction temperature range, T <sub>J</sub>		-40		125	°C

# 4 EVM Hardware and Software Setup

This section describes how to connect the different components of the EVM how to install the bq27530EVM PC software and.

# 4.1 Recommended Test Equipment

### 4.1.1 Power Supplies

- 1. Power Supply #1 (PS #1) capable of supplying 6 V at 3 A is required.
- 2. If not using a battery as the load, then power supply #2 (PS #2) capable of supplying up to 5 V at 5 A is required to power the circuit shown in Figure 7.

### 4.1.2 Load #1 Between BAT and GND

Testing with an actual battery is the best way to verify operation in the system. If a battery is not available, then a circuit similar to the one shown in Figure 7 can simulate a battery when connected to a power supply.



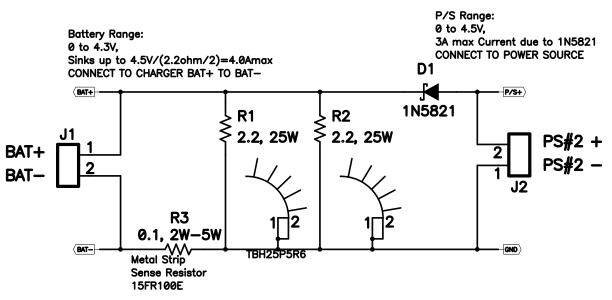


Figure 7. BAT\_Load (PR1010) Schematic

#### 4.1.3 Load #2 Between SYS and GND

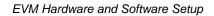
Although not required, a resistive load capable of sinking up to 3 A can be used.

#### 4.1.4 Meters

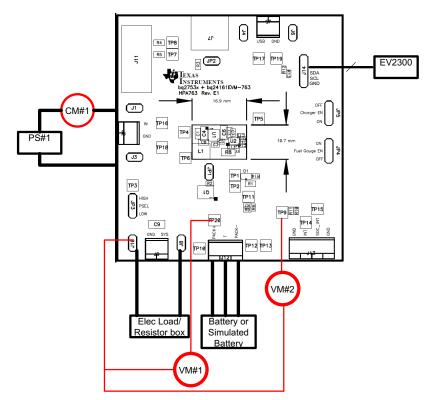
Four equivalent voltage meters (VM #) and two equivalent current meters (CM #) are required. The current meters must be able to measure 3-A current.

#### 4.1.5 Test Equipment Setup

- 1. For all power connections, use short, twisted-pair wires of appropriate gauge wire for the amount of the current.
- 2. Set Power Supply #1 (PS #1) for 6-V, 3-A current limit and then turn off supply.
- 3. If BAT\_Load as shown in Figure 8 is used, connect Power Supply #2 (PS #2) set to approximately 3.6 V to the input side (PS #2+/-) of BAT\_Load, then turn off PS #2.
- Connect the output side of the battery or BAT\_Load in series with current meter (multimeter) #2 (CM #2) to J2 and J6 or J3 (BAT, GND). Ensure that a voltage meter is connected across J2 or TP3 and J6 or TP9 (BAT, GND).
- 5. Connect VM #3 across J10 or TP7 and J14 or TP9 (SYS, GND).
- 6. Connect VM #4 across J15 or TP5 and J14 or TP9 (DRV, GND).
- 7. Ensure jumpers are at the default factory settings per Section 2.4
- 8. Connect I<sup>2</sup>C port of EV2300 with J14 board using the assembled 4 colored-wire connector included with EV2300 kit (GND / BLACK at the bottom).
- After the preceding steps have been performed, the test setup for HPA721 is configured as is shown in Figure 8







#### Figure 8. Original Test Setup for bq24160/161/163/168EVM (HPA721)

10. Turn on the computer. Open the bq27530 evaluation software. The main window of the software is shown in Figure 9 (DataRAM Screen)

#### 4.2 Software Installation

Find the latest software version at http://www.ti.com/tool/bqStudio. Use the following steps to install Battery Management Studio:

#### 4.2.1 Using EV2300

- 1. Ensure that the EV2300 is not connected to the PC through a USB cable before starting this procedure.
- 2. Select the Tool and Software tab in the product folder.
- 3. Under the Software section, click on Battery Management Studio (bqStudio) Software Suite.
- 4. Click the **Download** button to download the software.
- 5. Download software to hard drive.
- 6. Double-click the software executable and follow all instructions and prompts.

#### 4.2.2 Using EV2400:

- 1. Ensure that the EV2400 is not connected to the PC through a USB cable before starting this procedure.
- 2. Browse for the supported software link within the bq27530 TI web site product folder to find the downloadable EVSW installation files.
- 3. Open the software file that was downloaded from the TI web site.
- 4. Follow the instructions on screen until the software installation is completed.

#### 5 Troubleshooting Unexpected Dialog Boxes

The user that is downloading the files must be logged in as the administrator.

The driver is not signed, so the administrator must allow installation of unsigned drivers in the operating system policy.

#### 6 Operation

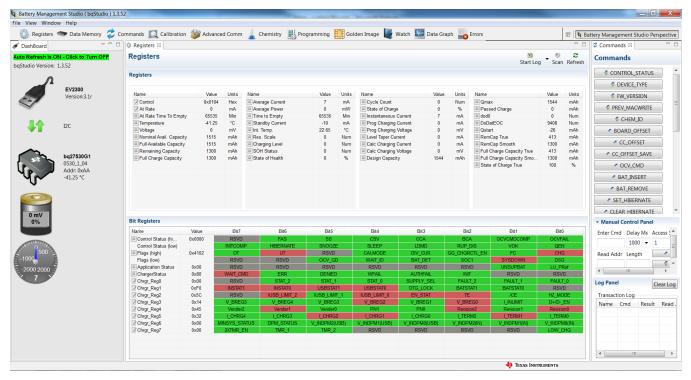
This section details the operation of the bqStudio software.

#### 6.1 Starting the Program

Run bqStudio from the Start | All Programs | Texas Instruments | Battery Management Studio. The main screen (Figure 9) appears. If instead of Figure 9 appearing, Figure 10 appears, it may mean that the EVM is not connected to the computer correctly. Make sure that the USB interface (EV2300 or EV2400 or GDK) and the bq27530 are connected and restart bqStudio. If this still does not resolve the issue, check if the I2C pullup resistors are connected. Data begins to appear once the <Refresh> (single-time scan) button is clicked, or when the Scan button is clicked. To disable the scan feature, simply click the **Scan** button again.

The continuous scanning period can be set by opening Window | Preferences  $\rightarrow$  Registers section. The range for this interval is 0 ms to 65,535 ms. Only items that are selected for scanning are scanned within this period.

Battery Management Studio provides a logging function which logs the values that were last scanned. To enable this function, select the Start Log button; this causes the Scan button to be pressed. When logging is Stopped, the Scan button will still be selected and has to be manually clicked again.



#### Figure 9. Registers Screen

This screen (Figure 9) shows the RAM data in the bq27530 device. Additional Flags and Status data can be viewed at the bottom of the Registers screen.

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Operation

a Target Selection Wizard	
Battery Management Studio (bqStudio) Supported Targets	
Please select a device type	
All Gauge Charger Wireless Charging Protector Reference Design	
Auto Detected Device : None	
If the type of device is not in the list above, you may download the latest version of bqStudio at <u>http://www.ti</u> . (new versions add support for newer devices)	.com/tool/bqstudio.
< Back Next > Finish	Cancel

### Figure 10. bqStudio Default Page

# 6.2 Setting Programmable bq27530 Options

The bq27530 data memory comes configured per the default settings detailed in the bq27530 technical reference manual. Ensure that the settings are correctly changed to match the pack and application for the bq27530 solution being evaluated.

**IMPORTANT:** The correct setting of these options is essential to get the best performance.

The settings can be configured using the Data Memory screen (Figure 11).



#### Calibration

www.ti.com

View Window Help					
🖄 Registers 🐡 Data Memory 💈	Commands 🔟 Calib	ration 🍟 Advanced Comm 🗼 Chemistry 🔣 Programming 臗 G	Golden Image 📲 Watch 🔚 Data Graph 🔤 Errors	📑 🖣 Ba	ttery Management Studio Perspect
DashBoard 🗸 🗖	Data Memory 🛛		· · · ·		💈 Commands 🛛 🗖
o Refresh is ON - Click to Turn OFF	Data Memory		Filter/Search	t Import Write_All Read All	Commands
tudio Version: 1.3.52			Auto Export Export	t import write_An Read An	
0	Read/Write Data	Memory Contents			CONTROL_STATUS
EV2300	Configuration	Name	Value	Unit ^	DEVICE_TYPE
Version:3.1r	configuration	▲ Safety			FW VERSION
~	Gas Gauging	Over Temp	60.0	°C	
	OCV Tables	Under Temp	0	°C	PREV_MACWRITE
		Temp Hys	3.0	°C	CHEM_ID
<b>12C</b>	Ra Tables	A Charge Termination			BOARD OFFSET
	Calibration	Charging Voltage	4200	mV	
		Taper Current	77	mA	CC_OFFSET
bg27530G1	Security	Min Taper Capacity	25	mAh	CC_OFFSET_SAVE
0530_1_04	Charger	Taper Voltage	100	mV	
Addr: 0xAA	charger	Current Taper Window	40	s	OCV_CMD
-41.25 °C		FC Clear %	98	% ≡	BAT_INSERT
9		FC Clear Volt	0	mV	BAT_REMOVE
		DODatEOC Delta T	5.0	°C	
		4 Data			SET_HIBERNATE
		Initial Standby	-10	mAh	CLEAR HIBERNATE
0 mV		CC Threshold	1390	mAh	
0%		Design Capacity	1544	mAh	<ul> <li>Manual Control Panel</li> </ul>
		SOH LoadI	-400	mA	Enter Cmd Delay Ms Acces
CTTTTTTTTTTTTTTTTTTTTTTTTTTTTTTTTTTTTT		Default Temperature	25.0	°C	1000 - 1
2500		Device Name	bq27530	-	
000 2		Data Flash Version	0000	Hex	Read Addr Length
000 2000		<ul> <li>Discharge</li> </ul>			
7		SOC1 Set Threshold	150	mAh	•
		SOC1 Clear Threshold	175	mAh	Log Panel Clear
		SysDown Set Volt Threshold	3150	mV	
		SysDown Set Volt Time	2	S	Transaction Log
		SysDown Clear Volt	3400	mV	Name Cmd Result R
		Final Voltage	3000	mV	
		Def Avg I Last Run	-299	mA	
		Def Avg P Last Run	-1131	mW	
		<ul> <li>Integrity Data</li> </ul>			
		Full Reset Counter	0	Num 👻	

Figure 11. Data Memory Screen

To read all the data from the bq27530 non-volatile flash memory, click on the **Read All** button on the *Data Memory* window. Make sure the device is not sealed and in full access to read or write to the data memory. To update a parameter, click on the desired parameter and a window pops-up that provides details on the selected parameter. Next, enter the value in the value textbox and press **Enter**. After pressing **Enter**, bqStudio updates the selected parameter. The **Import** button in the *Data Memory* window can be clicked in order to import an entire configuration from a specified \*.gg.csv file.

Save the configuration to a file by clicking the **Export** button in the *Data Memory* window and entering a file name. The configuration is saved to a \*.gg.csv file. The module calibration data is also held in the bq27530 data memory. If the Gauge Dashboard is not displaying any information, then the bq27530 may not be supported by the bqStudio version being used, a bqStudio upgrade may be required.

### 7 Calibration

The bq27530EVM must be calibrated to ensure accurate value reporting. This can be done by going to the Calibration window in bqStudio (Figure 12).

### 7.1 Calibrating the bq27530

Calibrate each item one at a time in the order presented in this document. Select the types of calibration to be performed by selecting the corresponding checkbox (see Figure 12).

Enter the measured values for the types selected, if necessary.

Then press the *Calibrate Part as indicated below* button. After all calibration is complete, close the Calibrate subwindow. While the Calibrate subwindow is open, even in the background, the calibration routines are running in firmware. Close the subwindow to ensure that they are stopped before proceeding with configuration or testing.

# 7.2 CC Offset Calibration

This performs the internal calibration of the coulomb counter input offset. Press the *Calibrate Coulomb Counter* button.



#### 7.3 Voltage Calibration

- Measure the voltage across Pack+ and Pack- with a calibrated meter.
- Type the voltage value in mV into Enter Actual Voltage.
- Measure the temperature for PACK.
- Type the temperature value into Enter Actual Temperature.
- Press the Calibrate Voltage and Temperature as indicated below button.

# 7.4 Board Offset Calibration

This performs the offset calibration for the current offset of the board. It takes approximately 35 seconds to complete.

It is expected that no current is flowing through the sense resistor while performing this calibration step. Remove load and short PACK– to GND.

Press the Calibration Board Offset button.

### 7.5 Pack Current Calibration

- Connect a load to GND and SYS that draws approximately 1 A, or connect a current source to GND and Pack–. Ensure that the Measured Current reported is negative, or else reverse the connections.
- Measure the current with a calibrated meter, and type the value into Enter Actual Current using (-) for current in discharge direction.
- Press the Calibrate Gas Gauge button.

Battery Management Studio ( bqStudio ) 1.3	.52	
File View Window Help		
🚳 Registers 🖘 Data Memory 💈 🤇	Commands 🔟 Calibration 👹 Advanced Comm 🚡 Chemistry 🔣 Programming 🏢 Golden Image 툍 Watch 🔚 Data Graph 🖺 Errors	😰 📔 Battery Management Studio Perspective
🖋 DashBoard 🗸 🗖 🗆	Calibration 🛙	Commands 🛛 🖓 🗆
Auto Refresh is ON - Click to Turn OFF	Calibration	Commands
bqStudio Version: 1.3.52	Perform Calibration	CONTROL_STATUS
EV2300	Select the type of calibration to perform and enter the actual input parameters.	DEVICE_TYPE
Version:3.1r	CC Offset	FW_VERSION
	Calibrate CC Offset	PREV_MACWRITE
<b>1</b> 2C		CHEM_ID
	Board Offset Calibrate Board Offset	BOARD_OFFSET
•		CC_OFFSET
bq27530G1 0530_1_04	Temperature	CC_OFFSET_SAVE
Addr: 0xAA -41.25 °C	Gauge Applied Temperature  Internal Temp  41.25 °C  deg ( Calibrate Tempera External Temp	OCV_CMD     AT_INSERT
-41.25 °C		BAT_REMOVE
	Current	E SET_HIBERNATE
0 mV	Gauge Applied Current 7 mA Calibrate Current	CLEAR HIBERNATE
0 mV 0%	Voltage	✓ Manual Control Panel
	Gauge Applied Voltage	Enter Cmd Delay Ms Access :
A STATE OF THE STA	0 mV Calibrate Voltage	1000 - 1
500 -1000 -	Calibrate Gas Gauge	Read Addr Length
-2000 2000		4
		Log Panel Clear Log
		Transaction Log
		Name Cmd Result Read.
	h Tau	s Instruments
	V IEXA	a Instruments



Calibration



Advanced Communication I2C

#### www.ti.com

### 8 Advanced Communication I2C

### 8.1 I<sup>2</sup>C Communication

l<sup>2</sup>C read/write operations are not specific to any gas gauge. These operations serve as general-purpose communication tools (Figure 13).

File View Window	v Help	5		
🚫 Registers 🕈	🤝 Data Memory 🛭 💈 Co	ommands 📃 Calibration 🏄 Advanced Comm 🗼 Chemistry 🔣 Programming 鼲 Golden Image 📗 Watch 🔚 Data Graph 🖳 Errors	😰 🖣 B	attery Management Studio Perspective
JashBoard	~	S Advanced Comm 😣		🖉 Commands 🛛 🗖 🗖
Auto Refresh is Of bgStudio Version: 1	N - Click to Turn OFF	Advanced Comm I2C Clear Log Sa	we Log Calculator	Commands
	10.02	12C Master Control Panel		CONTROL_STATUS
n		Byte Read/Write		DEVICE_TYPE
	EV2300 Version:3.1r	I2C Address (Hex) aa		FW_VERSION
		Start Register (Hex) 00		PREV_MACWRITE
		Bytes to Write (Hex) 08 A Write		CHEM_ID
41	12C	•		BOARD_OFFSET
		Number of Bytes to Read (Decimal) 4 Read		CC_OFFSET
	bq27530G1	Transaction Log		CC_OFFSET_SAVE
	0530_1_04 Addr: 0xAA	TimeStamp Rd/ Address Regist Len Data		OCV_CMD
Yr-	-41.25 °C			BAT_INSERT
•				BAT_REMOVE
				SET_HIBERNATE
0 mV				CLEAR HIBERNATE
0%				
				Enter Cmd Delay Ms Access : ^
The Designation				1000 • 1
-1000				Read Addr Length
-2000 2000				▼ <b>€</b> 4 IIII >
				Log Panel Clear Log
				Transaction Log
				Name Cmd Result Read.
				< III >
		h Taua luce		

#### Figure 13. Advanced Communication I<sup>2</sup>C

olden Image Expo	ort	
	ow you to export image files. memory contents of the connected gauge and save it to your hard drive in various formats.	
Output Directory	C:\ti\BatteryManagementStudio\OutputFiles	Browse
Base File Name	0520_3_29-bq27520G4	Dpen Directo
Output Formats		
SREC File (.srec	0520_3_29-bq27520G4.srec	Options
✓ BQFS File (.fs)	0520_3_29-bq27520G4.bq.fs	Options

Create Image Files

### Figure 14. Golden Image Output Screen

Programming	
Perform Programming	
This plug-in will allow you to program image files to a device.	
Select Programmable File	
	Browse
	Program
	Execute FW

# Figure 15. Perform Programming Screen



## 9 Related Documentation From Texas Instruments

To obtain a copy of any of the following TI documents, call the Texas Instruments Literature Response Center at (800) 477-8924 or the Product Information Center (PIC) at (972) 644-5580. When ordering, identify this document by its title and literature number. Updated documents also can be obtained through the TI Web site at www.ti.com.

• bq27530, System-Side Impedance Track<sup>™</sup> Fuel Gauge With Integrated LDO data sheet (SLUS955)

#### **Revision History**

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

#### Changes from A Revision (August 2013) to B Revision

Page

•	Deleted System Requirements and reworded Software Installation sections in EVM Hardware and Software Setup	15
•	Changed the entire Operation section, text and images	16
•	Changed Calibrate Screen section to Calibration section, and changed much of the text in the section	18
•	Changed I2C Pro Screen section to Advanced Communication I2C, changed some text and the images in this section.	20

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- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

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3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210

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